

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			New release	12/20'25	Larry

CUSTOMER DRAWING

RoHS Compliant

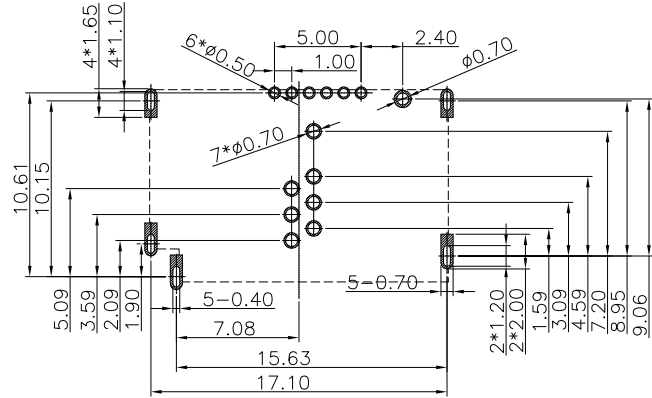
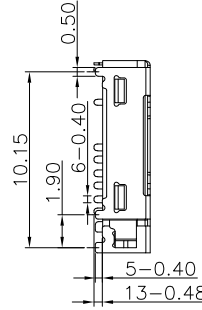
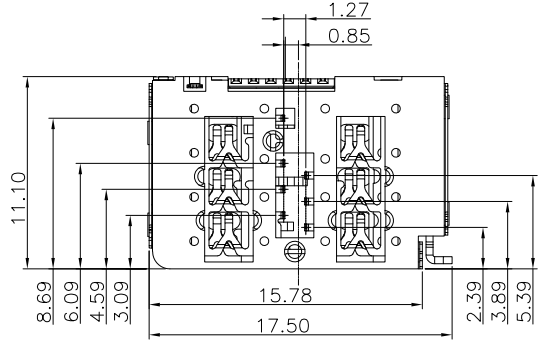
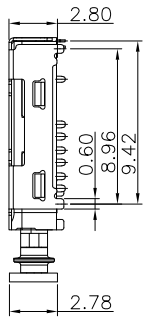
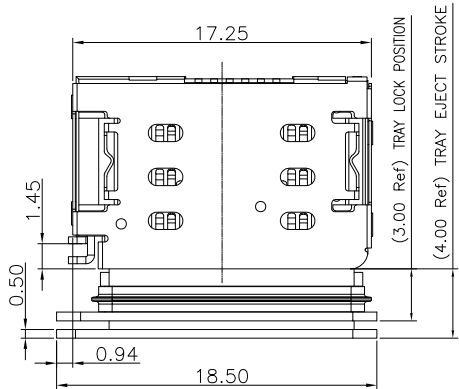
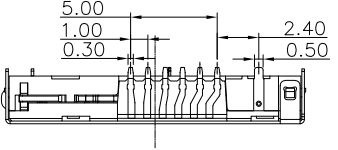
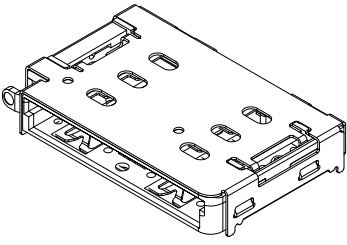
ORDERING INFORMATION

2SJN - Z01 (XX T)
 ① ② ③

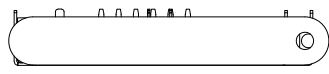
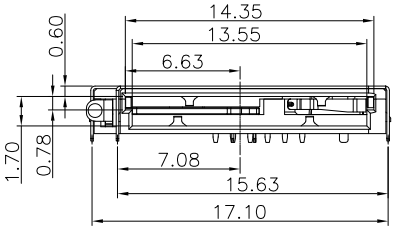
① **PRODUCT SERIES**
 2IN1 Socket -2.80H
 apply for Nano-SIM Card and Nano-SIM Card
 Tray type socket.

② **ITEM NO.**
 ③ **GOLD PLATING**
 01: G/F.

3D VIEW



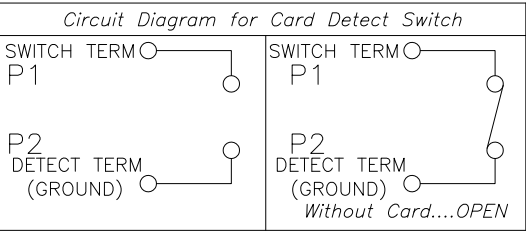
RECOMMEND P.C.B LAYOUT
 (General tolerance ±0.05)



Pin Define

Connector Pin No.	Pin Define
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
P1	SWITCH TERM
P2	DETECT TERM
P3~P7	GND

DIM	TOL	DIM	TOL
X.X	±0.35	X.X'	±3.0'
X.XX	±0.25	X.XX'	±2.0'
X.XXX	±0.15	X.XXX'	±1.0'



NOTES:

- MATERIAL:**
 - Housing: High Temp, LCP, UL 94V-0, Black Color.
 - Contact: Copper Alloy.
 - Shell: Stainless Steel.
- PLATING:**
 - Contact: Gold on contact area over Nickel plated overall. Gold on solder tails over Nickel plated overall.
 - Shell: Gold on solder tails over Nickel plated overall.
- SPECIFICATION:**
 - Current Rating :0.5A max.
 - Contact Resistance: 50 mOhms max
 - Insulation Resistance:1000 MOhms min./500VDC
 - Dielectric Withstanding Voltage:500 V AC/1minute
- Recommending A Metal More Than 0.15mm Thick.
 Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

SUNFUN		SUNFUN TECHNOLOGY LTD			
DRAW NO.	2SJN-Z01(A0)	DATE	12/20'25	MATERIAL:	SEE NOTES
DESIGN:	Larry	DATE	12/20'25	FINISH:	SEE NOTES
CHECK:	Larry	DATE	12/20'25	FILE:	2SJN-Z01(A0)
REVIEW:	Ziv	DATE	12/20'25	P/N:	2SJN-Z01(XXT)
APPROVED	Ziv	DATE	12/20'25	REV.	A0
		SCALE			
		DRAW NAME:	2IN1 Socket- 2.80H apply for Nano-SIM + Nano-SIM Tray type socket		
		MODEL:	Combo Card CONN		
UNIT:	mm	SHEET:	1/1		